Certificate TW16/01109

The management system of



Unimicron Technology Corporation

No. 179, Shanying Rd., Shanding Vil., Guishan Dist., Taoyuan, 333, Taiwan, R.O.C.

has been assessed and certified as meeting the requirements of

ISO 45001:2018

For the following activities

The R&D, design, sales, and manufacture of IC carrier, printed circuit boards.

This certificate is valid from 25 November 2022 until 25 November 2025 and remains valid subject to satisfactory surveillance audits.

Issue 5. Certified since 25 November 2019

Certified activities performed by additional sites are listed on subsequent pages.

Authorised by Stephen Pao Deputy Director

SGS Taiwan Ltd.

No. 136-1, Wu Kung Road, New Taipei Industrial Park, Wu Ku District, New Taipei City 24803, Taiwan t+886 (0)2 2299 3939 - www.sgs.com.tw







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Certificate TW16/01109, continued

Unimicron Technology Corporation



ISO 45001:2018

Issue 5

Sites

Unimicron Technology Corporation

No. 179, Shanying Rd., Shanding Vil., Guishan Dist., Taoyuan, 333, Taiwan, R.O.C.

The R&D, design, and sales of IC carrier, printed circuit boards.

Unimicron Technology Corporation Shanying I Plant

No. 177, 179, Shanying Rd., Shanding Vil., Guishan Dist., Taoyuan, 333, Taiwan, R.O.C.

The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (SY)

Unimicron Technology Corporation Shanying II Plant

No. 169, 169-2, Shanying Rd., Shanding Vil., Guishan Dist., Taoyuan, 333, Taiwan, R.O.C.

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package. (S2A)

Unimicron Technology Corporation Jingtzai 1st Plant

No. 175, 175-1, Shanying Rd., Shanding Vil., Guishan Dist., Taoyuan, 333, Taiwan, R.O.C.

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package (S1)

Unimicron Technology Corporation Jingtzai 2nd Plant

No. 173, 173-9, Shanying Rd., Shanding Vil., Guishan Dist., Taoyuan, 333, Taiwan, R.O.C.

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(S3)







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Certificate TW16/01109, continued

Unimicron Technology Corporation



ISO 45001:2018

Unimicron Technology Corporation Jingtzai 3rd Plant No. 173-1, 173-2, 171-2, 173-8, Shanying Rd., Shanding Vil., Guishan Dist., Taoyuan, 333, Taiwan, R.O.C.

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(S2)

Unimicron Technology Corporation Luchu II Plant

No. 21, Lane 470, Sec. 2, Nanshan Rd., Luzhu Dist., Taoyuan, 338, Taiwan, R.O.C.

The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (LC2)

Unimicron Technology Corporation Herjiang Plant

No. 12, Hejiang Rd., Zhongli Ind. Park, Taoyuan, 320, Taiwan, R.O.C.

The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (HJ)

Unimicron Technology Corporation Herjiang II Plant

No. 2, Hezun S. Rd., Zhongli Ind. Park, Taoyuan, 320, Taiwan, R.O.C.

The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (HJ2)







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